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CONFIRMATION NO. 1800

SERIAL NUMBER 10/735,355	FILING DATE 12/12/2003  RULE	CLASS 257	GROUP ART UNIT 2812	ATTORNEY DOCKET NO. MI22-2457
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## APPLICANTS

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## \*\* CONTINUING DATA \*\*\*\*\*

This application is a DIV of 10/340,126 01/10/2003 PAT 6,864,155  
 which is a DIV of 10/051,981 01/16/2002

yes JH

yes JH

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

none JH

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 03/23/2004

Foreign Priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	STATE OR COUNTRY ID	SHEETS DRAWING 3	TOTAL CLAIMS 14	INDEPENDENT CLAIMS 1
35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance				
Verified and Acknowledged Examiner's Signature <i>J. Kennedy</i> Initials <i>JH</i>				

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## TITLE

Wafer Bonding Method Of Forming Silicon-On-Insulator Comprising Integrated Circuitry

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